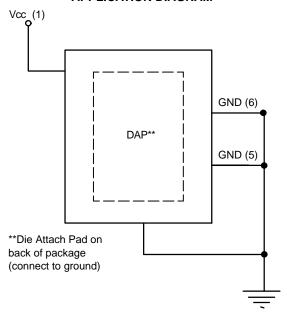
NSPM8151, NSPM8181

15 V and 18 V Unidirectional ESD and Surge Protection Device

Features

- Unidirectional High Voltage ESD & Surge Protection Device
- Provides ESD Protection to IEC61000-4-2 Level 4: ±30 kV Contact Discharge
- IEC 61000-4-5 (lighting)
- High Voltage Zener Diode Protects Supply Rail up to 100 A (8/20 μs)
- These Devices are Pb-Free and are RoHS Compliant

APPLICATION DIAGRAM





ON Semiconductor®

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UDFN6 D4 SUFFIX CASE 517CS

BLOCK DIAGRAM



MARKING DIAGRAM



Ax = Specific Device Code

x = 5 or E

M = Date Code

= Pb–Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
NSPM8151MUTBG	UDFN6 (Pb-Free)	3000 / Tape & Reel
NSPM8181MUTBG	UDFN6 (Pb-Free)	3000 / Tape & Reel

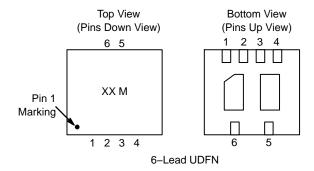
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NSPM8151, NSPM8181

Table 1. PIN DESCRIPTIONS

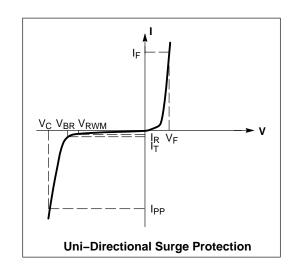
	4-Channel, 6-Lead, UDFN-8 Package					
Pin	Name	Туре	Description			
1	V _{CC}	HV V _{DD}	HV ESD Channel			
2	N/C		No Connect			
3	N/C		No Connect			
4	N/C		No Connect			
5	GND		Ground			
6	GND		Ground			

PACKAGE / PINOUT DIAGRAMS



ELECTRICAL CHARACTERISTICS

Symbol	Parameter				
I _{PP}	Maximum Reverse Peak Pulse Current				
V _C	Clamping Voltage @ I _{PP}				
V _{RWM}	Working Peak Reverse Voltage				
I _R	Maximum Reverse Leakage Current @ V _{RWM}				
V_{BR}	Breakdown Voltage @ I _T				
I _T	Test Current				
ΘV_{BR}	Maximum Temperature Coefficient of V _{BR}				
I _F	Forward Current				
V _F	Forward Voltage @ I _F				



SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter		Rating	Units
Operating Temperature Range		-55 to +125	°C
Storage Temperature Range		-65 to +150	°C
Peak Current (t _p = 8/20 μs)	NSPM8151	100	Α
Peak Current (t _p = 8/20 μs)	NSPM8181	119	Α

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS

		V _{RWM} (V)		Breakdown Voltage		Breakdown Voltage		V_C @ (8 x 20 μs)	
	Device	(Note 1)	I _R @ V _{RWM} (μΑ)	V _{BR} V (Note 2)		@ I _T (mA)	V _C (V)	I _{PP} (A)	
Device Name	Marking	Max	Max	Min	Nom	Max		Max	
NSPM8151	A5	15	1	16	17.5	18.5	1	27	100
NSPM8181	A8	18	1	20	22.5	23.5	1	28 30	70 100

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- A surge protector is normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal to or greater than the DC or continuous peak operating voltage level.
- 2. V_{BR} measured at pulse test current I_T at an ambient temperature of 25°C.
- 3. Surge current waveform per Figure 1.

NSPM8151, NSPM8181

TYPICAL CHARACTERISTICS

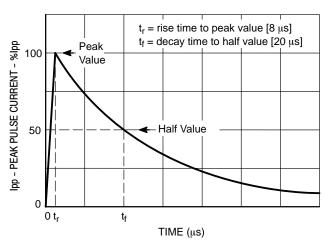
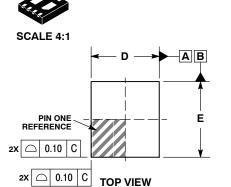
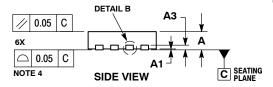


Figure 1. IEC61000-4-5 8/20 μs Pulse Waveform

DATE 30 APR 2013





DETAIL A

e1/2

2X D2 -

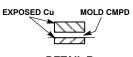
0.10 C

△ 0.10 C

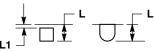
e1

BOTTOM VIEW

UDFN6, 1.8x2, 0.4P CASE 517CS **ISSUE 0**

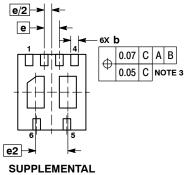


DETAIL B ALTERNATE CONSTRUCTION



ALTERNATE CONSTRUCTIONS





BOTTOM VIEW

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- 714.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION 6 APPLIES TO PLATED TERMINALS
 AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED PAD
- AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.45	0.55		
A1	0.00	0.05		
A3	0.125 REF			
b	0.15	0.25		
D	1.80 BSC			
D2	0.35	0.55		
E	2.00 BSC			
E2	0.74	0.94		
е	0.40 BSC			
e1	0.80 BSC			
e2	0.95 BSC			
L	0.20	0.40		
L1		0.15		

GENERIC MARKING DIAGRAM*

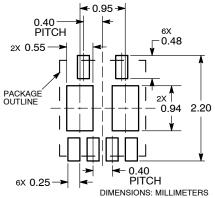


XX = Specific Device Code

= Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON89602E	Electronic versions are uncontrolled except when accessed directly from the Document Reposit Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	UDFN6 1.8X2, 0.4P		PAGE 1 OF 1		

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